

**650V N-Channel Super-Junction MOSFET**

## Features

- Fast Switching
- Low Gate Charge
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test
- Halogen Free

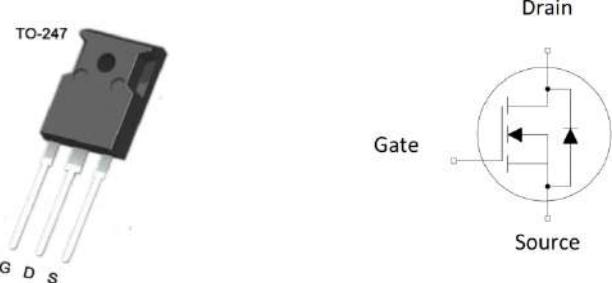
### Product Summary



$V_{DS}$	650	V
$R_{DS(on),Typ} @ V_{GS}=10\text{ V}$	91	$\text{m}\Omega$
$I_D$	40	A

## Application

- PC、Server power.



**Absolute** ( $T_J= 25^\circ\text{C}$  unless otherwise specified):

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-to-Source Voltage( $V_{GS}=0\text{V}$ )	650	V
$I_D$	Continuous Drain Current( $T_c=25^\circ\text{C}$ )	40	A
$I_{DM}$	Pulsed Drain Current( $T_c=25^\circ\text{C}$ )	120	A
$V_{GSS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy	1000	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$	50	V/ns
$dv/dt$	MOSFET $dv/dt$ ruggedness	100	V/ns
$di_f/dt$	Maximum diode communication speed	500	A/us
$P_D$	Power Dissipation( $T_c=25^\circ\text{C}$ )	338	W
$T_J, T_{stg}$	Operating and Storage Temperature Range	-55...+150	$^\circ\text{C}$
$T_L$	Maximum Temperature for Soldering	300	$^\circ\text{C}$

### Thermal Resistance

Symbol	Parameter	Max.	Units
$R_{\theta JC}$	Junction-to-Case	0.37	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient	55	$^\circ\text{C}/\text{W}$

### Notes

1. Limited by  $T_{jmax}$  Maximum duty cycle  $D=0.75$
2. Repetitive rating; pulse width limited by maximum junction temperature
3.  $L=20.0\text{mH}$ ,  $R_g=25\ \Omega$ ,  $V_{dd}=50\text{V}$ , Start  $T_j=25^\circ\text{C}$
4. identical low side and high side switch with identical  $R_g$

**650V N-Channel Super-Junction MOSFET**
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$  unless otherwise specified):

<b>OFF Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$V_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	650	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=250\mu\text{A}, \text{Reference } 25^\circ\text{C}$	--	0.74	--	$^\circ\text{C}$
$I_{DSS}$	Drain to Source Leakage Current	$V_{DS} = 650\text{V}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	10	$\mu\text{A}$
		$V_{DS} = 520\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$	--	--	500	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS} = +20\text{V} V_{DS} = 0\text{V},$	--	--	100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS} = -20\text{V} V_{DS} = 0\text{V},$	--	--	-100	nA

<b>ON Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10\text{V}, I_D=16\text{A}$	--	91	99	$\text{m}\Omega$
$V_{GS(\text{TH})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.5	3.9	4.5	V
Pulse width $t_p \leqslant 300\mu\text{s}, \delta \leqslant 2\%$						

<b>Dynamic Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_g$	Gate resistance	$f = 1.0\text{MHz}$	--	3.1	--	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V} V_{DS} = 100\text{V}$	--	3910	--	pF
$C_{oss}$	Output Capacitance	$f = 1.0\text{MHz}$	--	148	--	
$C_{rss}$	Reverse Transfer Capacitance		--	0.51	--	

<b>Resistive Switching Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D = 20\text{A} V_{DD} = 400\text{V}$ $R_G = 10\Omega$	--	31	--	ns
$t_r$	Rise Time		--	28	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	110	--	
$t_f$	Fall Time		--	55	--	
$Q_g$	Total Gate Charge	$I_D = 20\text{A} V_{DD} = 480\text{V}$ $V_{GS} = 10\text{V}$	--	70	--	nC
$Q_{gs}$	Gate to Source Charge		--	17	--	
$Q_{gd}$	Gate to Drain ("Miller") Charge		--	32	--	
$V_{plateau}$	Gate Plateau Voltage		--	6.2	--	V

**Source-Drain Diode Characteristics**

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I <sub>S</sub>	Continuous Source Current (Body Diode)	T <sub>C</sub> =25°C	--	--	40	A
I <sub>SM</sub>	Maximum Pulsed Current (Body Diode)		--	--	120	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =20A, V <sub>GS</sub> =0V	--	--	1.2	V
T <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =20A, T <sub>j</sub> = 25°C dI <sub>F</sub> /dt=100A/us, V <sub>GS</sub> =0V	--	140	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	750	--	nC
I <sub>rrm</sub>	Reverse Recovery Current		--	11	--	A

## 650V N-Channel Super-Junction MOSFET

### Characteristics Curve:

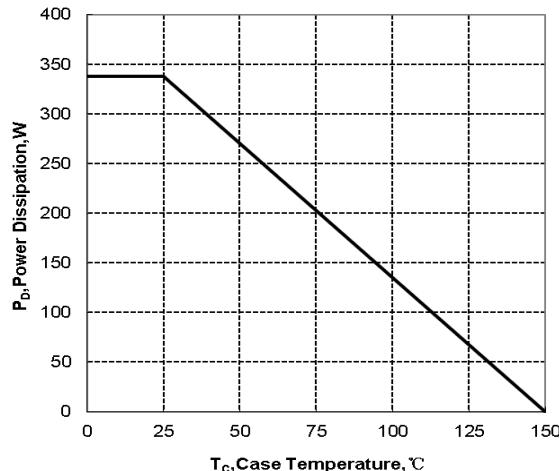
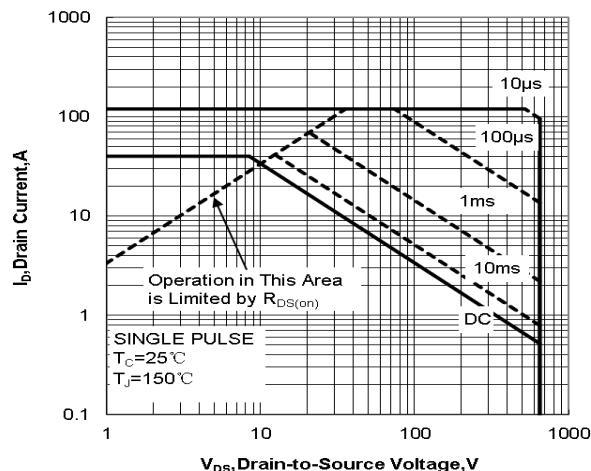


Figure 1 Maximum Forward Bias Safe Operating Area

Figure 2 Maximum Power Dissipation vs Case Temperature

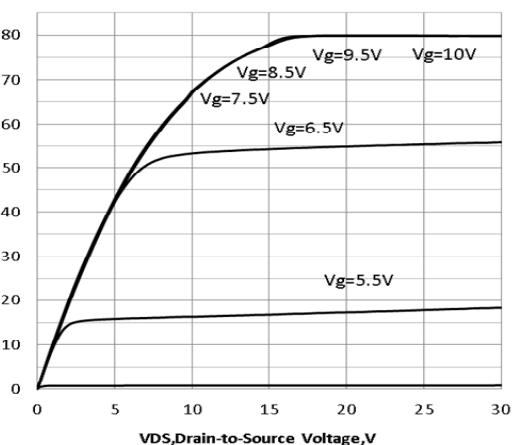
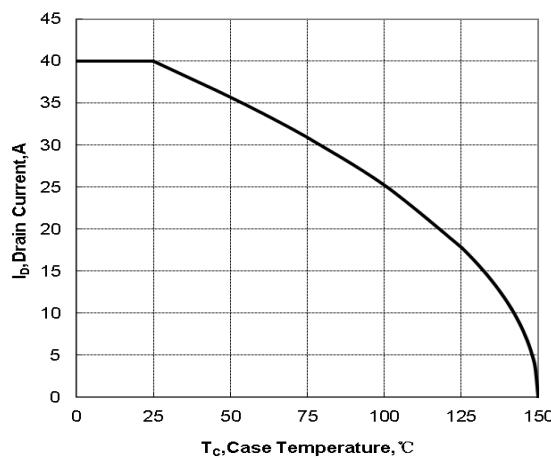
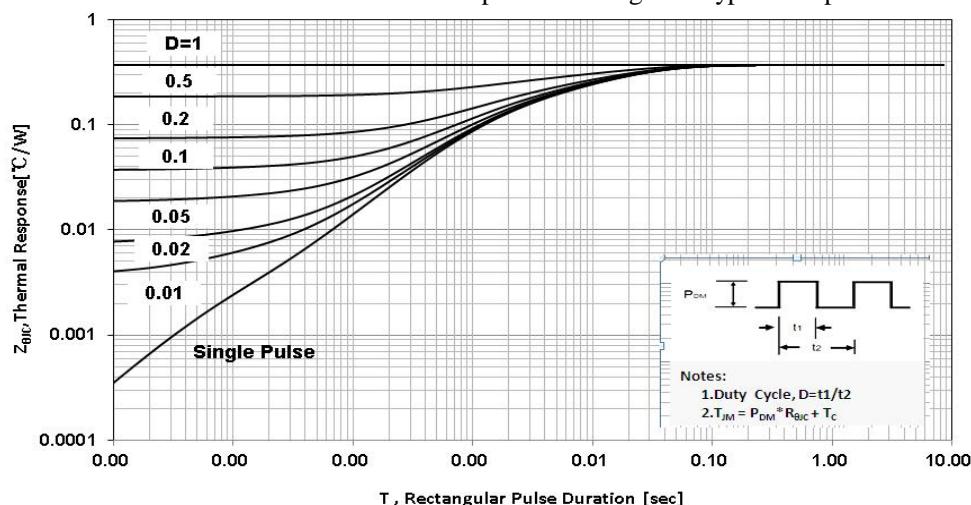


Figure 3 Maximum Continuous Drain Current vs Case Temperature

Figure 4 Typical Output Characteristics



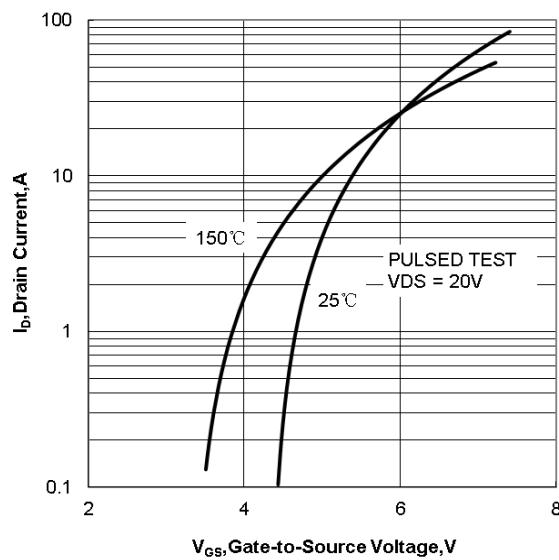
**650V N-Channel Super-Junction MOSFET**


Figure.6 Typical Transfer Characteristics

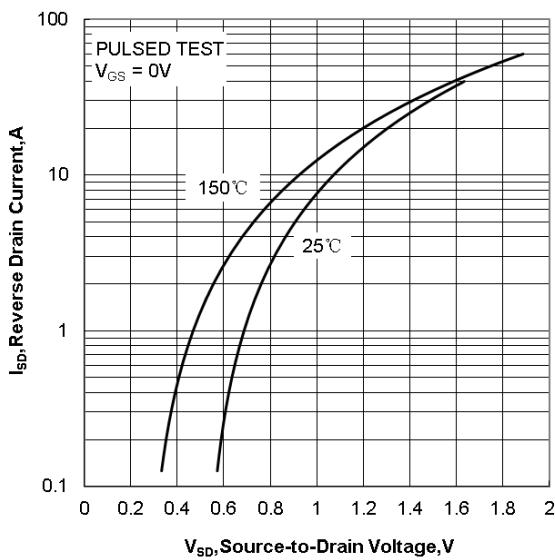


Figure.7 Typical Body Diode Transfer Characteristics

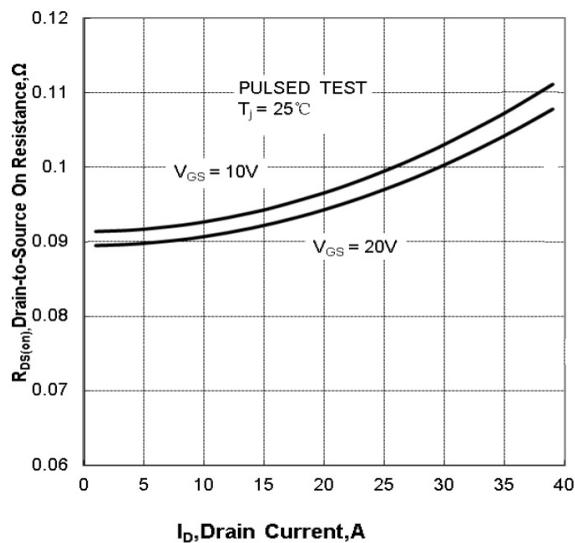


Figure.8 Typical Drain to Source ON Resistance vs Drain Current

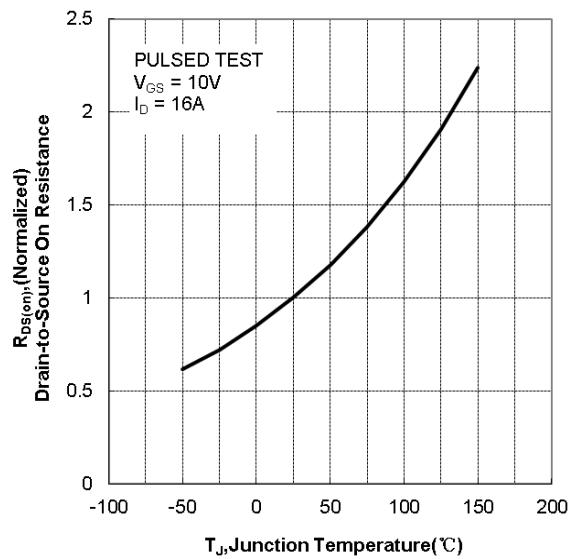


Figure.9 Typical Drian to Source on Resistance vs Junction Temperature

## 650V N-Channel Super-Junction MOSFET

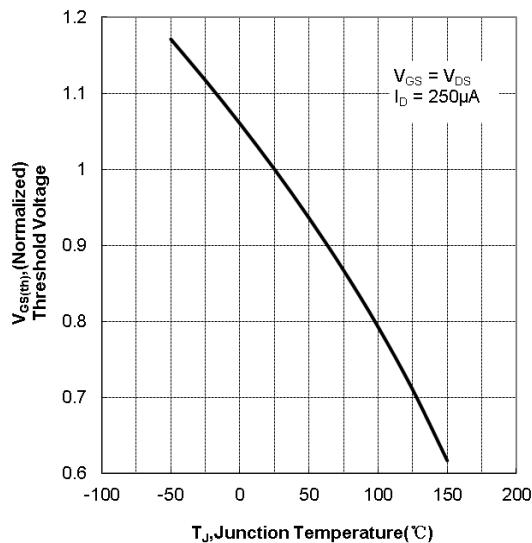


Figure.10 Typical Threshold Voltage vs Junction Temperature

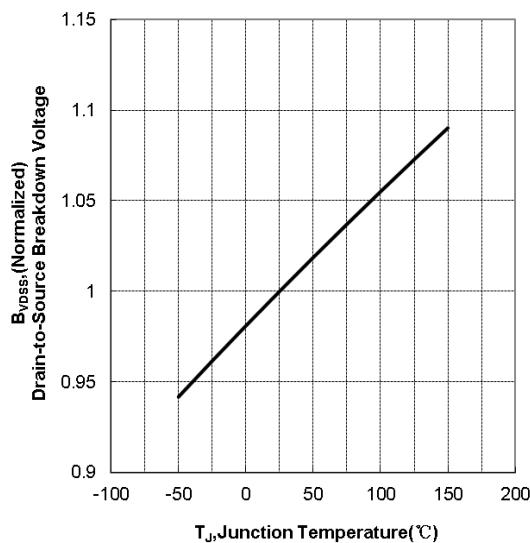


Figure 11 Typical Breakdown Voltage vs Junction Temperature

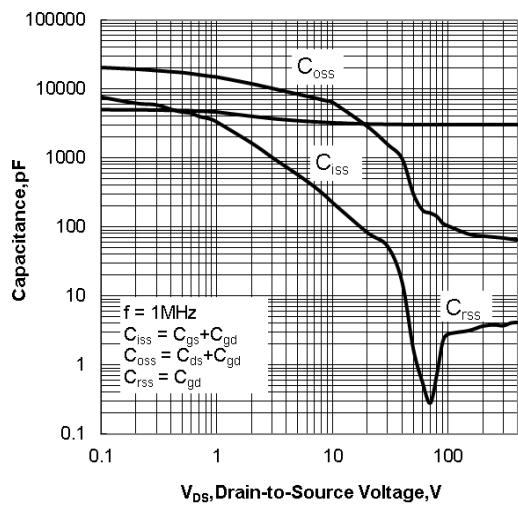


Figure.12 Typical Capacitance vs Drain to Source Voltage

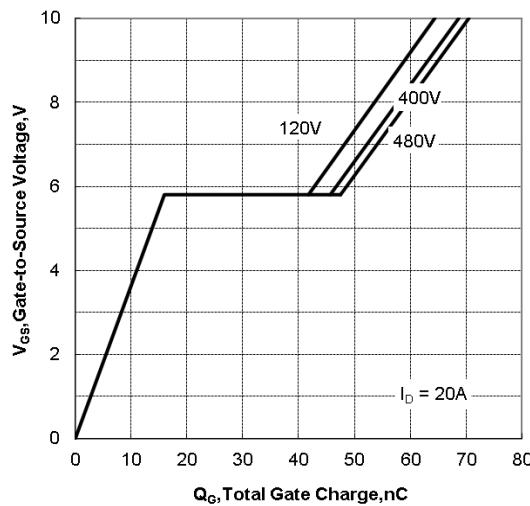


Figure.13 Typical Gate Charge vs Gate to Source Voltage

## Test Circuit and Waveform

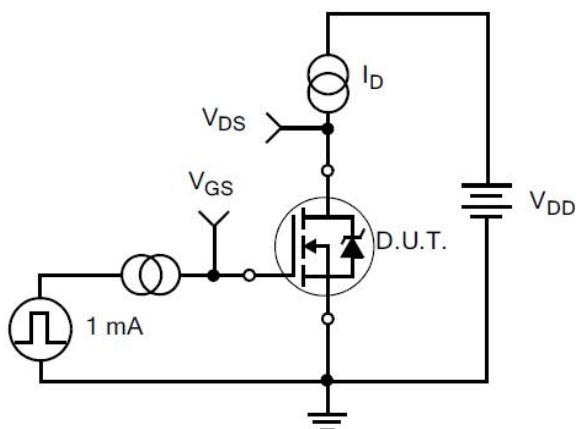


Figure 14. Gate Charge Test Circuit

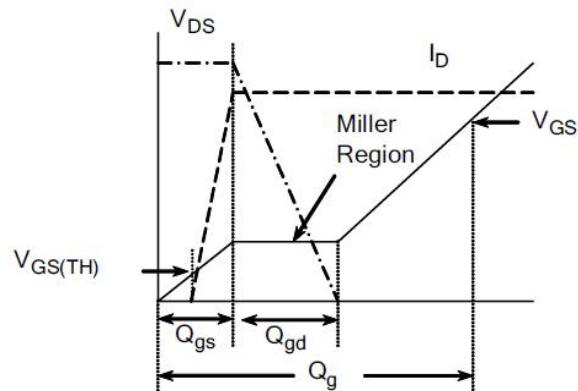


Figure 15. Gate Charge Waveforms

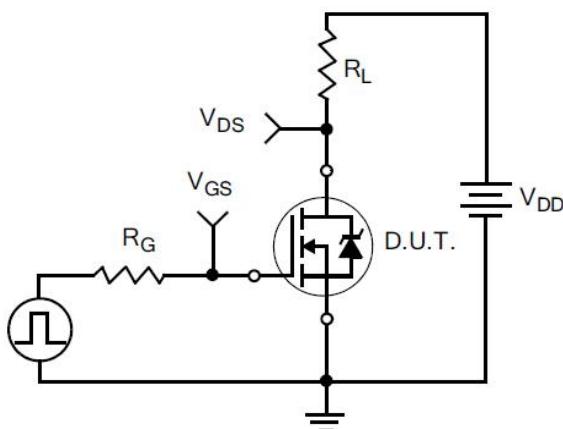


Figure 16. Resistive Switching Test Circuit

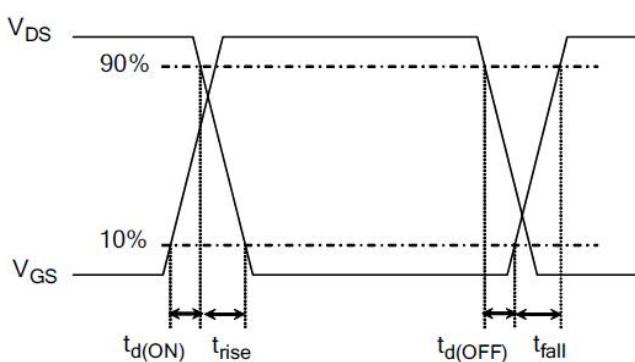
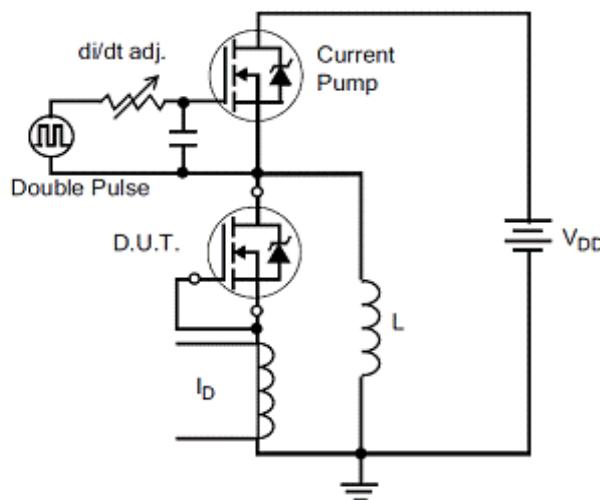
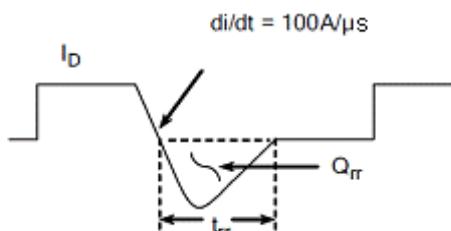


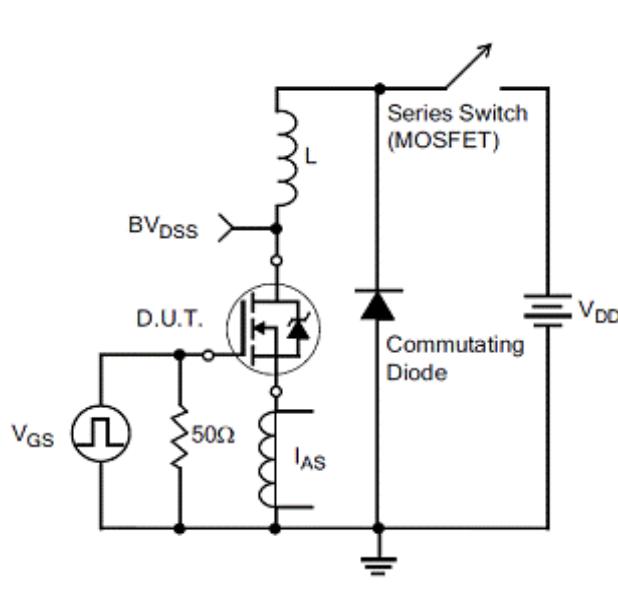
Figure 17. Resistive Switching Waveforms

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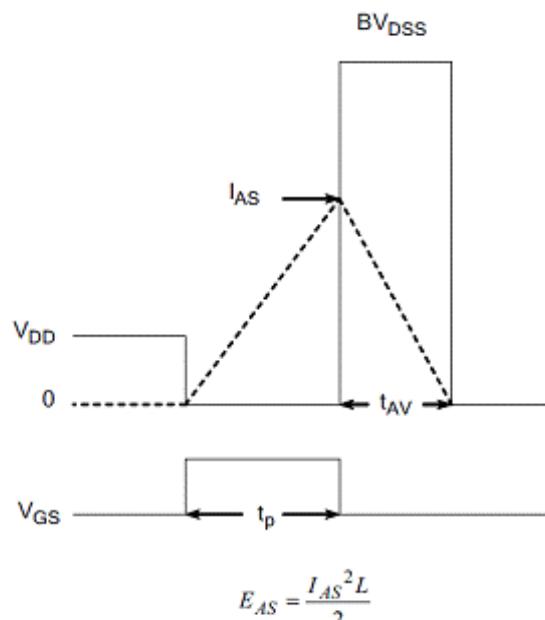
**Figure 18. Diode Reverse Recovery Test Circuit**



**Figure 19. Diode Reverse Recovery Waveform**



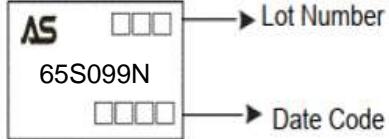
**Figure20.Unclamped Inductive Switching Test Circuit**



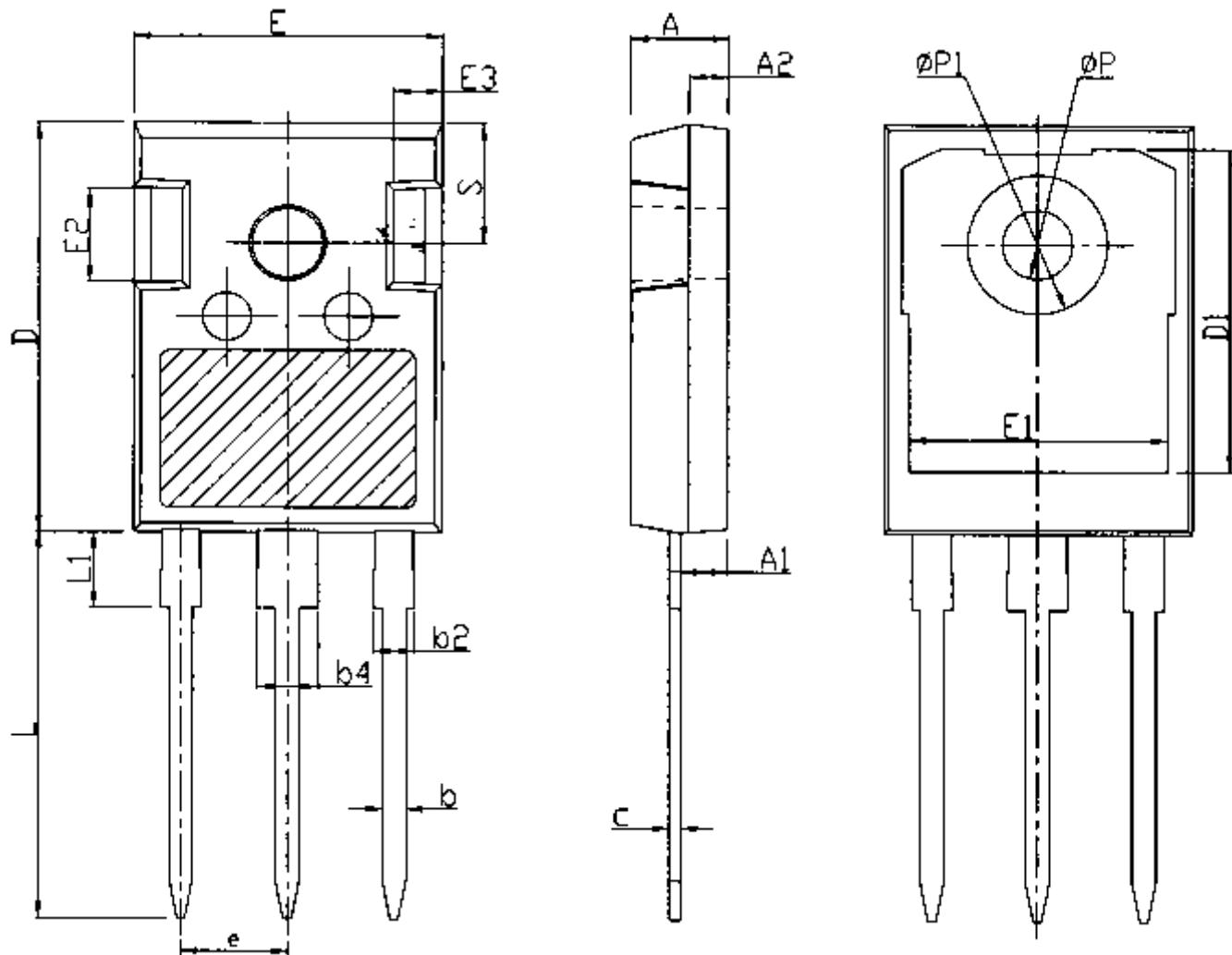
**Figure21.Unclamped Inductive Switching Waveform**

## Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM65S099NX-R	65S099N	TO-247	Tube	30/Tube

PACKAGE	MARKING
TO-247	

**650V N-Channel Super-Junction MOSFET**  
**TO-247**



Unit:mm			
Symbol	Min.	Nom	Max.
A	4.80	5.00	5.20
A1	2.21	2.41	2.61
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16.25	16.55	16.85

Unit:mm			
Symbol	Min.	Nom.	Max.
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44BSC		
L	19.62	19.92	20.22
L1	-	-	4.30
$\Phi P$	3.40	3.60	3.80
$\Phi P1$	-	-	7.30
S	6.15BSC		

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